

## ABSTRACT OF THE DISCLOSURE

A first semiconductor chip 102 includes an integrated circuit formed on a face which is shown upwards in FIG. 2. A second  
5 semiconductor chip 103 includes an integrated circuit formed on a face which is shown downwards in FIG. 2. Between the first semiconductor chip 102 and the second semiconductor chip 103, a non-conductive die pad 107 is interposed. The die pad 107 is provided with connection members 110 protruding from the first  
10 semiconductor chip 102 and the second semiconductor chip 103. The connection members 110 are plated on their surfaces so as to be electrically conductive. The integrated circuit on the first semiconductor chip 102 and the integrated circuit on the second semiconductor chip 103 are interconnected by two inter-chip  
15 connection wires 104a and 104b, via the connection members 110. Thus, there is provided a semiconductor device composed of a plurality of internally connected semiconductor chips, such that the semiconductor device is easy to produce and requires a reduced number of component elements.